

# **Additional Information**



Resources





Accessories

Samples

# **Description**

The 30R Series radial leaded device is designed to provide overcurrent protection for low voltage (≤30V) applications where space is not a concern and resettable protection is

### **Features & Benefits**

- Cured, flame retardant epoxy polymer insulating material meets UL 94V-0 requirements
- Fast time-to-trip
- RoHS compliant, Lead-Free and Halogen-Free\*

# **Applications**

- USB hubs, ports and peripherals
- Computers & peripherals
- Motor protection
- General electronics
- Automotive applications

### **Agency Approvals**

Agency	Agency File Number
c <b>SN</b> °us	E74889
$\triangle$	R72161784

#### **Electrical Characteristics**

			v		P <sub>d</sub>	Maximum	Γime To Trip	Resis	tance	Agency A	pprovals
Part Number	(A)	(A)	(Vdc)	(A) typ. (W)	typ. (W)	Current (A)	Time (Sec.)	R <sub>min</sub> (Ω)	R <sub>1max</sub> (Ω)	c <b>'911</b> ° us	<b>A</b>
30R090U	0.90	1.80	30	40	0.6	4.50	5.90	0.070	0.220	Χ	X
30R110U	1.10	2.20	30	40	0.7	5.50	6.60	0.050	0.170	Χ	Χ
30R135U	1.35	2.70	30	40	0.8	6.75	7.30	0.040	0.130	X	Χ
30R160U	1.60	3.20	30	40	0.9	8.00	8.00	0.030	0.110	Χ	X
30R185U	1.85	3.70	30	40	1.0	9.25	8.70	0.030	0.090	Χ	X
30R250U	2.50	5.00	30	40	1.2	12.50	10.30	0.020	0.070	Χ	X
30R300U	3.00	6.00	30	40	2.0	15.00	10.80	0.020	0.080	Χ	X
30R400U	4.00	8.00	30	40	2.5	20.00	12.70	0.010	0.050	X	Χ
30R500U	5.00	10.00	30	40	3.0	25.00	14.50	0.010	0.050	Χ	Χ
30R600U	6.00	12.00	30	40	3.5	30.00	16.00	0.005	0.040	Χ	X
30R700U	7.00	14.00	30	40	3.8	35.00	17.50	0.005	0.030	Χ	X
30R800U	8.00	16.00	30	40	4.0	40.00	18.80	0.005	0.020	Χ	X
30R900U	9.00	18.00	30	40	4.2	40.00	20.00	0.005	0.020	Χ	Χ

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

- I hold = Hold current: maximum current device will pass without tripping in 20°C still air.

- $t_{trip} = Trip$  current: minimum current at which the device will trip in 20°C still air.  $t_{trip} = Trip$  current: minimum current at which the device will trip in 20°C still air.  $t_{trip} = Trip$  current: minimum current at which the device without damage at rated current (I max)  $t_{trip} = Trip$  current: minimum current device can withstand without damage at rated voltage ( $t_{trip} = t_{trip} = t_{trip$
- $I_{\text{max}}$  = Maximum fault current userice can without the state at 20°C still air.  $I_{\text{max}}$  = Power dissipated from device when in the tripped state at 20°C still air.

- $\mathbf{R}_{\min}$  = Minimum resistance of device in initial (un-soldered) state.
- R typ = Typical resistance of device in initial (un-soldered) state. R <sub>1max</sub> = Maximum resistance of device at 20°C measured one hour after tripping.
- \* Effective February 11, 2010 onward, all 600R PTC products will be manufactured Halogen Free (HF). Existing Non-Halogen Free 600R PTC products may continue to be sold, until supplies are depleted. This change will have no effect on 600R product specifications or performance.

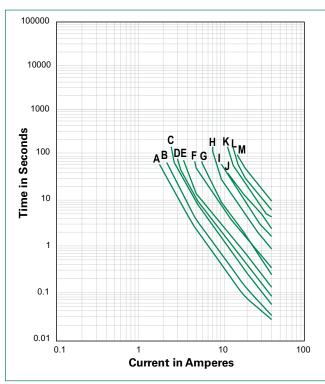
- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device



### **Temperature Rerating**

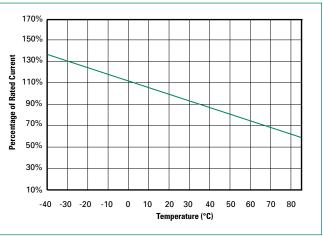
	Ambient Operation Temperature								
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Part Number				I	Hold Current (A	)			
30R090U	1.31	1.17	1.04	0.90	0.75	0.69	0.61	0.55	0.47
30R110U	1.60	1.43	1.27	1.10	0.91	0.85	0.75	0.67	0.57
30R135U	1.96	1.76	1.55	1.35	1.12	1.04	0.92	0.82	0.70
30R160U	2.32	2.08	1.84	1.60	1.33	1.23	1.09	0.98	0.83
30R185U	2.68	2.41	2.13	1.85	1.54	1.42	1.26	1.13	0.96
30R250U	3.63	3.25	2.88	2.50	2.08	1.93	1.70	1.53	1.30
30R300U	4.35	3.90	3.45	3.00	2.49	2.31	2.04	1.83	1.56
30R400U	5.80	5.20	4.60	4.00	3.32	3.08	2.72	2.44	2.08
30R500U	7.25	6.50	5.75	5.00	4.15	3.85	3.40	3.05	2.60
30R600U	8.70	7.80	6.90	6.00	4.98	4.62	4.08	3.66	3.12
30R700U	10.15	9.10	8.05	7.00	5.81	5.39	4.76	4.27	3.64
30R800U	11.60	10.40	9.20	8.00	6.64	6.16	5.44	4.88	4.16
30R900U	13.05	11.70	10.35	9.00	7.47	6.93	6.12	5.49	4.68

### **Average Time Current Curves**



The average time current curves and Temperature Rerating curve performance is affected by a number or variables, and these curves provided as guidance only. Customer must verify the performance in their application.

### **Temperature Rerating Curve**

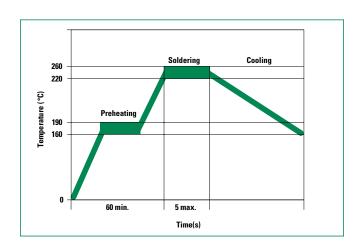


Note: Typical Temperature rerating curve, refer to table for derating data



# **Soldering Parameters - Wave Soldering**

Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer.  Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C. Time within 5°C of actual Max. solder temperature within 3 - 5 seconds. Total time from 25°C room to Max. solder temperature within 5 minutes including Pre-Heating time.
Cooling Zone	Cooling by natural convection in air.  Max. ramping down rate should not exceed 6°C/ Sec.



## **Physical Specifications**

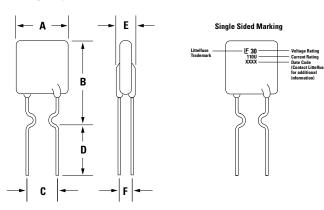
Lead Material	0.90-1.85A: Tin-plated Copper clad steel 2.50-9.00A: Tin-plated Copper
Soldering Characteristics	Solderability per MIL-STD-202, Method 208
Insulating Material	Cured, flame retardant epoxy polymer meets UL94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

# **Environmental Specifications**

Operating Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 1000 hours -/+5% typical resistance change
Thermal Shock	+85°C to -40°C 10 times -/+5% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Moisture Resistance Level	Level 1, J-STD-020

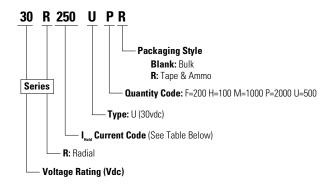


# **Dimensions & Part Marking System**



	А		В	3	С	;	D		E		F		Physica	l Chara	cteristics
Part Number	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Lead (	dia)	Matarial
Nullibei	Max.	Max.	Max.	Max.	Тур.	Тур.	Min.	Min.	Max.	Max.	Тур.	Тур.	Inches	mm	Material
30R090U	0.29	7.40	0.48	12.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R110U	0.29	7.40	0.56	14.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R135U	0.35	8.90	0.53	13.50	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R160U	0.35	8.90	0.60	15.20	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R185U	0.40	10.20	0.62	15.70	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/CuFe
30R250U	0.45	11.40	0.72	18.30	0.20	5.10	0.30	7.60	0.12	3.00	0.039	1.0	0.02	0.51	Sn/Cu
30R300U	0.45	11.40	0.76	19.20	0.20	5.10	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R400U	0.55	14.00	0.87	22.00	0.20	5.10	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R500U	0.55	14.00	1.01	25.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R600U	0.65	16.50	1.06	26.80	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R700U	0.75	19.10	1.13	28.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R800U	0.85	21.60	1.22	31.10	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu
30R900U	0.95	24.10	1.24	31.60	0.40	10.20	0.30	7.60	0.12	3.00	0.047	1.2	0.03	0.81	Sn/Cu

# **Part Ordering Number System**

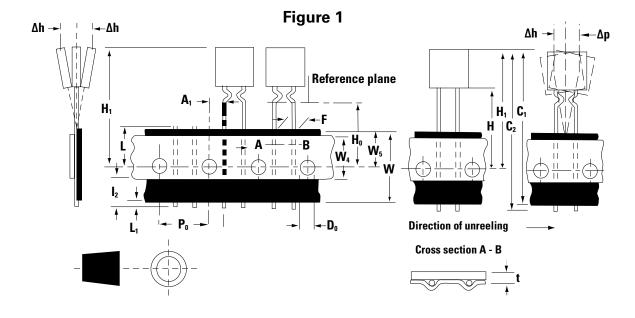




## **Packaging**

Part Number	Ordering Number	I <sub>hold</sub> (A)	I <sub>hold</sub> Code	Packaging Option	Quantity	Quantity & Packaging Codes
30R090U	30R090UU 30R090UPR	0.90	090	Bulk Tape and Ammo	500 2000	U PR
	30R110UU			Bulk	500	U
30R110U	30R110UPR	1.10	110	Tape and Ammo	2000	PR
30R135U	30R135UU	1.35	135	Bulk	500	Ü
300 1330	30R135UPR	1.30	130	Tape and Ammo	2000	PR
30R160U	30R160UU	1.60	160	Bulk	500	U
300 1000	30R160UPR	1.60	160	Tape and Ammo	2000	PR
20D10ELL	30R185UU	1.05	105	Bulk	500	U
30R185U	30R185UPR	1.85	185	Tape and Ammo	2000	PR
30R250U	30R250UU	2.50	250	Bulk	500	U
30h2500	30R250UPR	2.50	250	Tape and Ammo	2000	PR
20020011	30R300UU	3.00	200	Bulk	500	U
30R300U	30R300UPR	3.00	300	Tape and Ammo	2000	PR
20040011	30R400UF	4.00	400	Bulk	200	F
30R400U	30R400UMR	4.00	400	Tape and Ammo	1000	MR
30R500U	30R500UF	5.00	FOO	Bulk	200	F
3005000	30R500UMR	5.00	500	Tape and Ammo	1000	MR
30R600U	30R600UF	6.00	600	Bulk	200	F
3000000	30R600UMR	6.00	600	Tape and Ammo	1000	MR
30R700U	30R700UMR	7.00	700	Tape and Ammo	1000	MR
30R800U	30R800UH	8.00	800	Bulk	100	Н
20000011	30R900UH	9.00	900	Bulk	100	Н
30R900U	30R900UMR	9.00	900	Tape and Ammo	1000	MR

### **Tape and Ammo Diagram**





### **Tape and Ammo Specifications**

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension	EIA Maul	IEC Mayl	Dimensions			
Dimension	EIA Mark	IEC Mark	Dim. (mm)	Tol. (mm)		
Carrier tape width	W	W	18	-0.5 / +1.0		
Hold down tape width:	$W_{_4}$	W <sub>o</sub>	11	min.		
Top distance between tape edges	$W_{_{6}}$	W <sub>2</sub>	3	max.		
Sprocket hole position	$W_{_{5}}$	W <sub>1</sub>	9	-0.5 / +0.75		
Sprocket hole diameter*	$D_{\scriptscriptstyle{0}}$	D <sub>o</sub>	4	-0.32 / +0.2		
Abscissa to plane(straight lead)	Н	Н	18.5	-/+ 3.0		
Abscissa to plane(kinked lead)	H <sub>o</sub>	H <sub>o</sub>	16	-/+ 0.5		
Abscissa to top: 30R090-30R185	H <sub>1</sub>	H <sub>1</sub>	32.2	max.		
Abscissa to top: 30R250-30R900	-	-	45.0	max.		
Overall width w/o lead protrusion: 30R090- 30R185	<b>C</b> <sub>1</sub>	-	42.5	max.		
Overall width w/o lead protrusion: 30R250-30R900	-	-	56	max.		
Overall width w/ lead protrusion: 30R090-30R185	$\mathbf{C_2}$	-	43.2	max.		
Overall width w/ lead protrusion: 30R250-30R900	-	-	57	max.		
Lead protrusion	L <sub>1</sub>	I <sub>1</sub>	1.0	max.		
Protrusion of cut out	L	L	11	max.		
Protrusion beyond hold-down tape	$\mathbf{I}_2$	$\mathbf{I}_2$	Not specified	-		
Sprocket hole pitch: 30R090-30R300	$P_{o}$	P <sub>o</sub>	12.7	-/+ 0.3		
Sprocket hole pitch on: 30R400-30R900	$P_{o}$	P <sub>o</sub>	25.4	-/+ 0.5		
Device pitch: 30R090-30R300	-	-	12.7	-		
Device pitch: 30R400-30R900	-	-	25.4	-		
Pitch tolerance	-	-	20 consecutive.	-/+ 1		
Tape thickness	t	t	0.9	max.		
Tape thickness with splice: 30R090-30R250	t,	-	1.5	max.		
Tape thickness with splice: 30R300-30R900	t,	-	2.0	max.		
Splice sprocket hole alignment	-	-	0	-/+ 0.3		
Body lateral deviation	Δh	Δh	0	-/+ 1.0		
Body tape plane deviation	Δр	Δр	0	-/+ 1.3		
Ordinate to adjacent component lead*	P <sub>1</sub>	P <sub>1</sub>	3.81	-/+ 0.7		
Ordinate to adjacent component lead*	-	-	7.62	-/+ 0.7		
Lead spacing: 30R090-30R400	F	F	5.08	-/+ 0.8		
Lead spacing: 30R500-30R900	F	F	10.18	-/+ 0.8		

### Note: \*Differs from EIA Specification

### Warning

- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
   These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
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   Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device.

